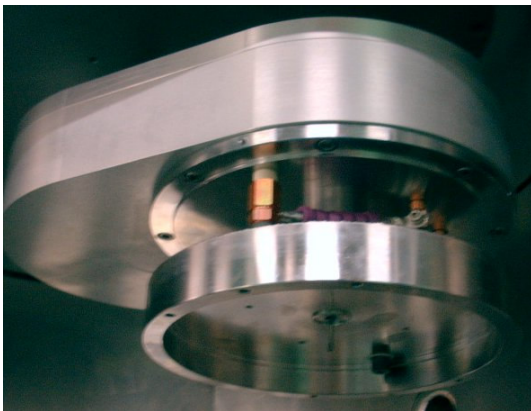
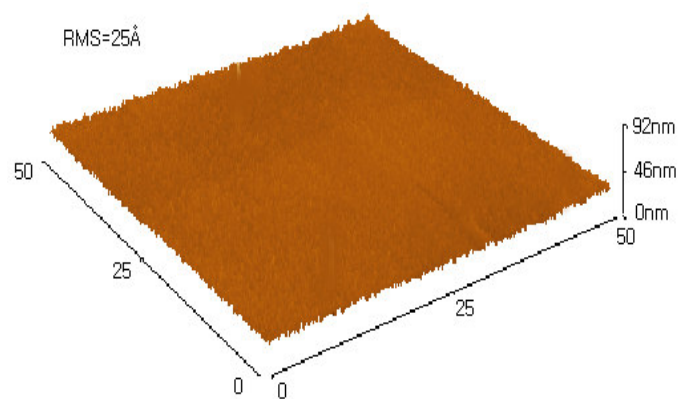


ATS-PVD Series RF Sputtering System with 2x7" and 2x4" Guns



AFM image of silica layer



Special Features

- ◆ RF sputtering system for R&D and small scale production
- ◆ Excellent thickness uniformity and surface morphology in deposited layers
- ◆ Silicon and reactive silicon oxide deposition
- ◆ Automatically movable substrate holder

◆ Applications

Optical device
Optical wave guide
Passivation layer

◆ Wafer capacity

1 × 6"

◆ Average throughput

Up to 5,000 wafers per year

◆ Dimension

1730L × 1277H × 725W (mm³)

◆ Others

Power: AC 1.2kW (13.56MHz)

AC 600W (13.56MHz)

DC 1kW (optional)

Gas : Ar / O₂

Heater : silicon carbide

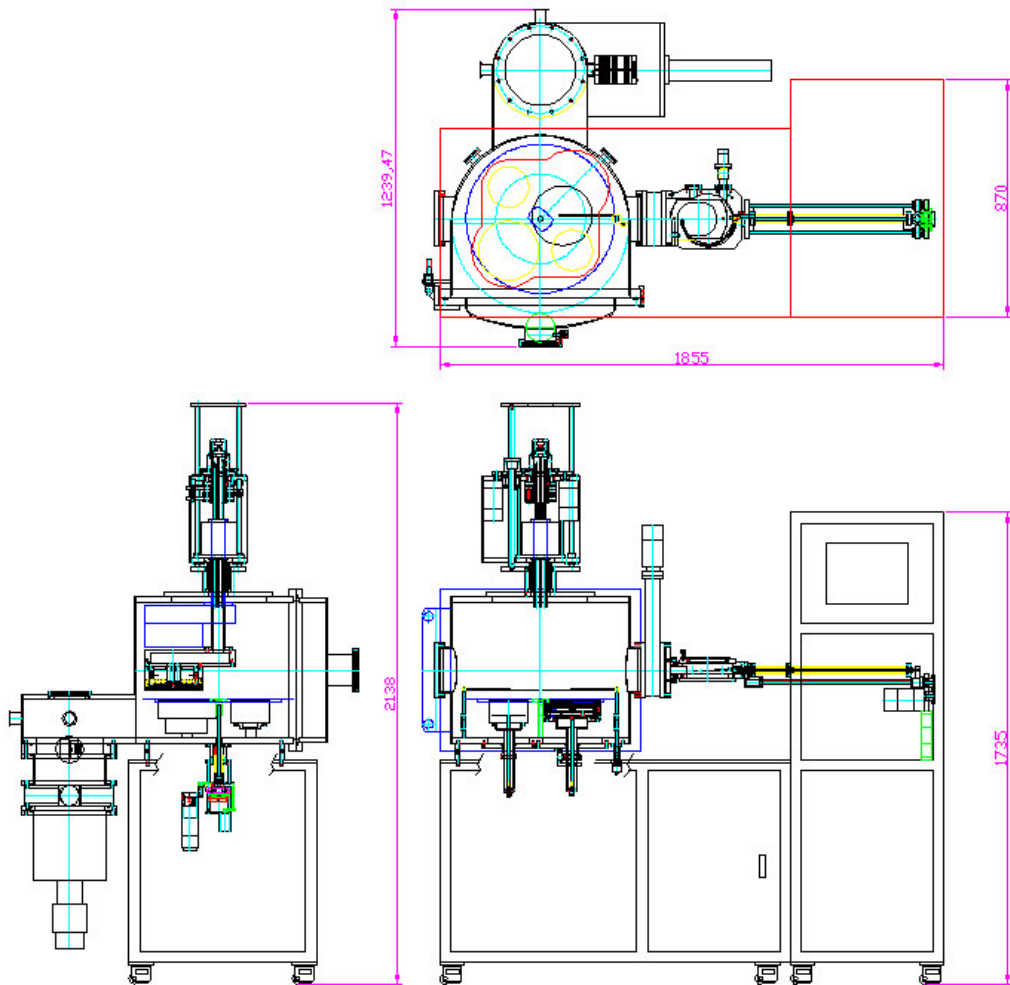
(heating rate: 40°C/min, max.

temp.:850°C, deviation: negligible)

Pump : rotary(600l/mim) &

cryogenic(900l/s)

◇ Layout



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